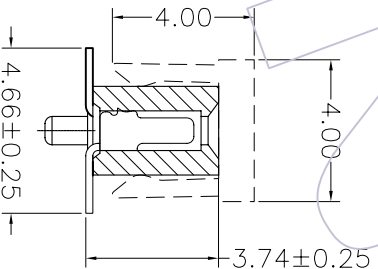
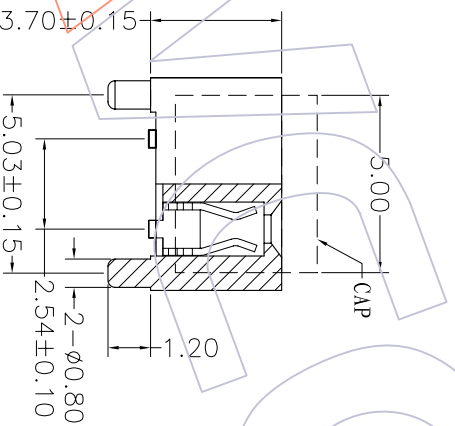
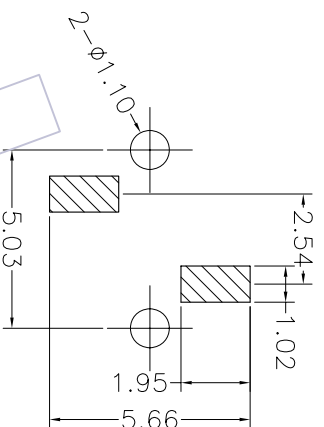
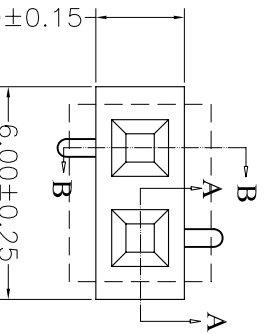


HSF

Recommended P.C.B Layout(TOP Side)
(PCB BOARD TOLERANCE±0.05)

NOTES:

Current Rating: 3.0AMP
Withstand Voltage: 500V AC/DC
Contact Resistance: 20mΩ Max
Insulation Resistance: 1000MΩMin
Operation Temperature: -40°C to +105°C
Contact Material: Phosphor Bronze
Contact plating: Au or Sn over Ni
Insulator Material: PA6T+30%G, F UL94V-0



Ordering Information

2135 - 1 02 M XX C U N T X

Contact Plating:
G1=Gold Finish
G1=3μ Gold
G2=5μ Gold
G3=10μ Gold
G4=15μ Gold
G5=30μ Gold
SP=Gold Flash/Tin
S1=3μ Gold/Tin
S2=5μ Gold/Tin
S3=10μ Gold/Tin
S4=15μ Gold/Tin
S5=30μ Gold/Tin
SN=Tin

Packing:
T=Tube
P=Tube+CAP
R=Tray&Reel+CAP

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION	DRAW	WEIXD	SCALE	UNIT	PART NO.	WAVE HARDWARE ELECTRONICS CO. LTD
A0	08/03/01	NEW			XX ±0.40	DESIGN	08.03.11	5:1	mm	2135-102MXXCUNTX	维峰五金电子有限公司
					X.XX ±0.25	CHECK		A4			WAPE HARDWARE ELECTRONICS CO. LTD
					X.XXX ±0.15	APPROVE		1/1			
					Angle ± 3°			PROJ.			
					DM						
					TOL						

WCON 维峰五金电子有限公司
WAPE HARDWARE ELECTRONICS CO. LTD

2135-102MXXCUNTX
PH2.54 SINGLE SWT H=3.5 2Pin WITH POST